ABSTRACT

A semiconductor wafer surface protection sheet which can prevent breakage of a semiconductor wafer even when a circuit-formed surface of the semiconductor wafer has a significant unevenness, and a method for protecting the semiconductor wafer by using such protection sheet.

The semiconductor wafer surface protection sheet includes at least one resin layer (A) satisfying a relationship of G' (60) / G' (25) < 0.1, where G' (25) is a storage elastic modulus at 25°C, and G' (60) is a storage elastic modulus at 60°C The semiconductor wafer protecting method using such sheet is also provided.